TEMPERATURE CONTROL DEVICE, PLASMA ETCHING APPARATUS, AND SEMICONDUCTOR MANUFACTURING SYSTEM

ABSTRACT

A temperature control device (1) includes a valve device (2), a first fluid supply device (40) configured to supply a first fluid to the valve device (2), a second fluid supply device (50) configured to supply a second fluid to the valve device (2), and a supply pipe portion (61) configured to allow the first fluid, the second fluid, or the first fluid and the second fluid flowing out of the valve device (2), to flow, and performs temperature control by a fluid flowing through the supply pipe portion (61). The valve device (2) includes a first valve member (10) and a second valve member (20) that are in contact with each other and are relatively rotatable while maintaining a contact state. The first fluid, the second fluid, or the first fluid and the second fluid are supplied from the valve device (2) to the supply pipe portion (61) according to the relative rotation between the first valve member (10) and the second valve member (20).
Fig. 1